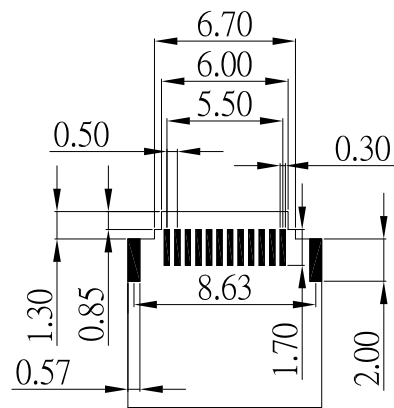
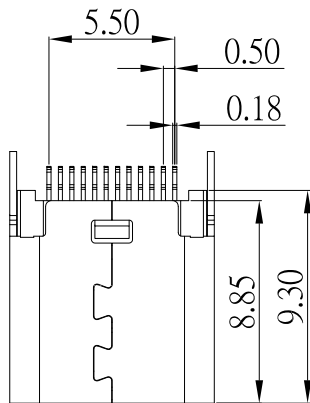
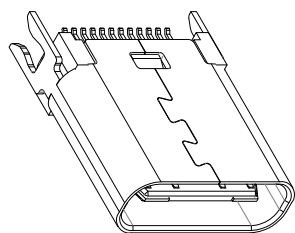




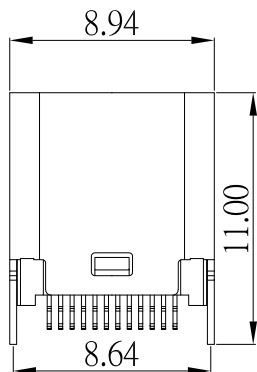
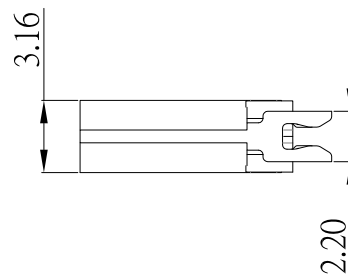
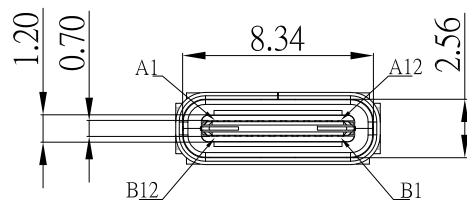
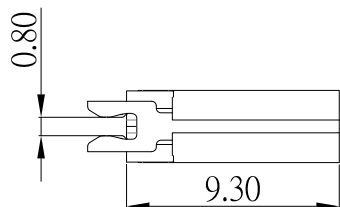
SBC-240V4-31x-S271

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"



PCB LAYOUT



**SPECIFICATIONS**

**Electrical:**

- 1.Rating: 3.0 A
- 2.Dielectric Withstand Voltage: 100V AC
- 3.Contact Resistance: 40 mΩ Max
- 4.Insulation Resistance: 100 MΩ Min

**Material:**

- 1.Housing: LCP,
- 2.Contact: PHOSPHOR BRONZE
- 3.Shell: SUS

**Finish:**

- 1.Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer

**CONTACT** 建倚科技股份有限公司  
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :  
Up to 5 ±0.2  
Above 5 ~ 15 ±0.3  
Above 15 ~ 30 ±0.4  
Above 30 ~ 50 ±0.5  
Angle ±0.3°

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	08/16/17		MODLE	USB 3.1 TYPE C 夾板母座
CHECKED BY:	DATE	FINISH	DWG NO.	SBC-240V4-31x-S271
Jacky Chen	08/16/17		PART NO.	SBC-240V4-31x-S271
APPROVED BY:	DATE	SCALE	1 of 1	
Tony Kao	08/16/17	SHEET NO.		

1	新增pcb layout	Jack	081617
ITEM NO.	DESCRIPTION	DRAWN	DATE